

CRYOGENIC ENGINEERING CONFERENCE & INTERNATIONAL CRYOGENIC MATERIALS CONFERENCE

Dena'ina Civic & Convention Center

Anchorage, Alaska, USA & June 17 - 21, 2013

http://www.cec-icmc.org

2013 CALL FOR ABSTRACTS & PAPERS

We invite you to participate in the 2013 Cryogenic Engineering Conference (CEC) and International Cryogenic Materials Conference (ICMC) to be jointly held from June 17 to June 21, 2013 at the Dena'ina Civic and Convention Center, Anchorage, Alaska, USA. The conference program format will consist of plenary, focused, and special sessions with oral and poster presentations covering all aspects of cryogenic engineering and materials. In addition, an extensive exhibit will showcase the most up-to-date products and technologies in the cryogenic field.

Anchorage is a unique destination located in one of the world's most spectacular settings – Alaska. Recognized as a four-time All-America City, Anchorage is a modern city surrounded by spectacular wilderness with adventures just steps from downtown. The city possesses all the cultural amenities and activities one would expect from any urban center, but this one just happens to be surrounded by wilderness of mountains and valleys, glaciers and fjords, active and inactive volcanoes. Anchorage is known as both the "City of Lights" (winter) and the "City of Flowers" (summer). During summer the days seem endless. Dazzling displays of flowers adorn homes and storefronts, live music fills the air, while king and silver salmon are caught right downtown in Ship Creek. At first mention, Anchorage may stir up visions of igloos and Eskimos, but Alaska's largest city is nothing like that at all. Much warmer than you may think, Anchorage sees an average temperature of around 68 degrees Fahrenheit (20 degrees Celsius) in the summer.

CALL FOR ABSTRACTS & PAPERS

Authors are requested to submit abstracts and papers that address any aspect of cryogenic engineering and cryogenic materials research. The submission categories are listed below for the CEC and the ICMC respectively.

The subject matter of submitted abstracts and papers should be technically orientated and feature new, original developments in cryogenic engineering and materials. Manuscripts will be peer reviewed for possible publication by the American Institute of Physics in the conference transactions, *Advances in Cryogenic Engineering*. The mode of presentation (oral or poster) will have no effect on the review of the submitted paper. Acceptance of an abstract for presentation does not guarantee publication in the conference transactions.

PREPARING ABSTRACTS

Submission of abstracts for CEC-ICMC will be <u>entirely</u> electronic, using the conference website, www.cec-icmc.org. Complete information regarding the format of abstracts and submission categories can be found at this website. *The deadline to submit abstracts is January 11, 2013*.

ABSTRACT ACCEPTANCE & MANUSCRIPT SUBMISSION

Abstract acceptance letters will be emailed by **February 25**, 2013. Instructions on manuscript preparation and submission will be posted on the website. *The deadline for electronic submission of manuscripts is June 18*, 2013.

To allow time for potential foreign participants to file their Visa applications in a timely manner, abstracts generated by foreign participants should be submitted as early as possible. The conference organizers will endeavor to respond quickly to these abstracts as they come in. (Please see the "VISA Requirements" section below.)

EXHIBITS

A technical exhibition of materials, services, instruments and literature will take place during the conference. If you or your company are interested or would like to receive additional information about the CEC-ICMC 2013 Exhibition, you may visit the conference website or contact Centennial Conferences at Phone: (001) 303-499-2299, Fax: (001) 303-499-2599, Email: cecicmc@centennialconferences.com.

FINANCIAL SUPPORT

A limited amount of financial support in the form of a waived registration is available for students and attendees from developing countries presenting papers. The guidelines for requesting assistance are available on the web page. *The deadline to apply is February 15, 2013.*

AWARDS AND SCHOLARSHIPS

Participants are encouraged to submit nominations to the CEC and ICMC for the awards that will be presented during the conference. Further information on submitting nominations or applying is available at www.cec-icmc.org.

The Samuel Collins Award honors major contributions to cryogenic engineering. *The deadline for nominations is December 21, 2012.*

The ICMC Cryogenic Materials Award for Lifetime Achievement is given in recognition of lifetime achievements in advancing the knowledge of cryogenic materials. *The deadline for nominations is April 19, 2013.*

The Russell B. Scott Best Paper Award will be selected from the CEC papers presented at the 2011 Conference. Please see the conference web page for more information on this award.

The CEC Timmerhaus Scholarship is a graduate scholarship intended to "develop and foster increased interest and participation in fields of cryogenic studies and to encourage future engineers and scientists in these areas". *The deadline for applications is May 15, 2013.*

CEC and ICMC Student Meritorious Paper Award is awarded to students for outstanding work. Winners will receive a printed certificate and a monetary award. *The deadline for applications is April 13, 2013.*

ICMC Best Paper Awards will be selected from the papers presented at the 2011 Conference. Please see the conference web page for more information on this award.

CEC and ICMC Student Travel Awards are available for a limited number of students presenting papers at the conference. *The deadline for travel assistance applications is April 13, 2013.*

NOMINATIONS FOR THE CEC BOARD

Individuals wishing to nominate a person or themselves for the CEC Board elections are requested to contact:

Thomas H. Nicol Fermilab P.O. Box 500, Rm. 41-208 Batavia, IL 60510

Phone: (001) 630-840-3441 • Fax: (001) 630-840-8036 • Email: tnicol@fnal.gov

The deadline for nominations is January 11, 2013.

VISA REQUIREMENTS

Citizens of countries outside the U.S. must carry a valid passport and may be required to obtain a visa to enter the U.S. As the visa process may take up to 6 months, foreign participants should contact the United States Embassy, Consulate or Office of Tourism in their home country as soon as possible to determine their individual visa requirements. CEC-ICMC 2013 CANNOT INTERVENE with either U.S. Embassies abroad or with the State Department in Washington, DC, on behalf of any participant. However, if you need a personal letter of invitation to attend the Conference, contact Centennial Conferences (email: cecicmc@centennialconferences.com; Fax: (001) 303-499-2599) and provide your full name, complete mailing address, a valid email address, and your phone and fax numbers. Your letter will be EMAILED TO YOU. A hard copy will be faxed and mailed to you via regular airmail only if requested. Any fees for sending letters via express mail must be paid for by the requester.

CONFERENCE INFORMATION

All conference related information will be made available on the conference website at http://www.cec-icmc.org. For any additional conference inquiries, please contact the Conference Management at:

Centennial Conferences

917 Front Street, Suite 220, Louisville, CO 80027, USA

Phone: (001) 303-499-2299 • Fax: (001) 303-499-2599 • Email: cecicmc@centennialconferences.com

CEC-ICMC SUBMISSION CATEGORIES

CEC SUBMISSION CATEGORIES		ICMC SUBMISSION CATEGORIES
CEC-01	Large-Scale Refrigeration and Liquefaction	ICMC-01 Ferrous Metals at Cryogenic Temperatures
CEC-02	Large-Scale Systems, Facilities, and Testing	ICMC-02 Non-Ferrous Metals at Cryogenic Temperatures
CEC-03	Pulse Tube Cryocoolers (Non-aerospace)	ICMC-03 Non-Metallic Materials at Cryogenic Temperatures
CEC-04	Magnetic, Stirling, and Other Coolers (Non-	ICMC-04 Polymers, Resins, and Composite Materials at
	aerospace)	Cryogenic Temperatures
CEC-05	Expanders, Pumps, and Compressors	ICMC-05 Nb-Ti and Other LT Alloy Superconductors
CEC-06	Regenerators	ICMC-06 Niobium3-Tin Superconductors
CEC-07	Stirling and Pulse Tube Cryocoolers (Aerospace)	ICMC-07 A-15 and Other Compound Superconductors
CEC-08	Magnetic, Sorption, and Other Coolers (Aerospace)	ICMC-08 Thin Film HTS and LTS Superconductors
CEC-09	LTS Superconducting Magnet Systems	ICMC-09 HTS BSCCO Wires and Tapes
CEC-10	HTS Superconducting Magnet Systems	ICMC-10 HTS Coated Conductors, Processing and Properties
CEC-11	Superconducting RF Systems	ICMC-11 Flux Pinning Centers in HTS, Preparation/Properties
CEC-12	Cryogenic Power Cables and Leads	ICMC-12 High Current HTS Cables, Conductor Composites
CEC-13	Energy, Transportation, and Fuels	ICMC-13 ReBCO Bulk Superconductors
CEC-14	Power Applications, Systems, and Materials	ICMC-14 Pnictides (Films, Wires, Bulk, Single Crystals)
CEC-15	Aerospace and Space Launch	ICMC-15 Novel Superconducting Materials
CEC-16	Safety, Reliability, and Standards	ICMC-16 Superconductor Stability and AC Losses
CEC-17	Fluid Mechanics, Heat Transfer, and Cryogen	ICMC-17 Mechanical Properties of LTS Materials
	Properties	ICMC-18 Mechanical Properties of HTS Materials
CEC-18	Helium II Properties and Systems	ICMC-19 Mechanical Properties of Structure Materials, Fatigue
CEC-19	Thermal Insulation Systems	ICMC-20 Radiation Effects in Materials
CEC-20	Instrumentation and Controls	ICMC-21 Cryogenic Processing of Materials (Metals, Polymers,
CEC-21	Environmental Process Applications	Biomaterials and Others)
CEC-22	Cryogenic Applications in Industry and	ICMC-22 Materials Evaluation and Testing Methods at
	Manufacturing	Cryogenic Temperature
CEC-23	Cryogenics for Medical and Food Applications	ICMC-23 Novel Materials, Processes, Properties and
CEC-24	Novel Concepts and New Devices	Applications
		ICMC-24 Cryogenic Power Electronics, Materials and Systems
		Highlighted topics
		ICMC-25 MgB2 Precursors, Bulk, Wires, Tapes and Cables
		ICMC-26 Material Properties of Magnets and Coils
		ICMC-27 Insulating materials at Cryogenic Temperatures and
		High Voltage Properties

PROGRAM SUGGESTIONS

Suggestions concerning the technical program, particularly topical workshops and special sessions, should be directed to the appropriate Conference or Program Chair.

conductors

CEC:

Conference Chair Peter Shirron NASA/Goddard Space Flight Center Code 552 Greenbelt, MD 20771

Phone: (301) 286-7327

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ICMC:

Conference Chair

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Program Vice-Chair

ICMC-28 Nanostructures in Structure Materials and Super-

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<u>DATES TO REMEMBER</u>		
End of November, 2012	Abstract Submission Opens	
December 21, 2012	Samuel C. Collins Award Nomination Deadline	
January 11, 2013	Abstract Submission Deadline	
January 11, 2013	CEC Board Nominations Deadline	
February 15, 2013	Financial Support Application Deadline	
February 25, 2013	Emailed Notification of Abstract Acceptance	
March 1, 2013	Conference Registration Opens	
March 1, 2013	Hotel Reservation Opens	
April 13, 2013	Student Travel Award Application Deadline	
April 13, 2013	Student Meritorious Paper Award Application Deadline	
April 19, 2013	ICMC Lifetime Achievement Award Nomination Deadline	
April 17, 2013	Early Conference Registration Fee Deadline	
May 1, 2013	Hotel Reservation Deadline	
May 15, 2013	CEC Klaus Timmerhaus Scholarship Award Application Deadline	
June 3, 2013	Pre-Conference Registration Deadline	
Mid May, 2013	Manuscript Submission Site Opens	
June 17 - 21, 2013	CONFERENCE	
June 18, 2013	Manuscript Submission Deadline	

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